



Docket No.: M4065.0082/P082-A
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Paul A. Farrar

Application No.: 09/638,026

Filed: August 14, 2000

For: METHOD OF FORMING A MICRO
SOLDER BALL FOR USE IN C4
BONDING PROCESS

Group Art Unit: 2811

Examiner: N. Parekh

Commissioner for Patents
Washington, DC 20231

#3

1-16-02

J. Flower

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REQUEST FOR RECONSIDERATION

Dear Sir:

In response to the Office Action dated September 28, 2001 (Paper No. 2),
please consider the following remarks.

REMARKS

Claims 40-51 and 68-70 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Yamamoto in view of Akram and “admitted prior art” (hereinafter “APA”). Claims 71 and 72 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Yamamoto in view of Akram and APA. Claim 73 stands rejected under 35 U.S.C. §103(a) as being unpatentable over Yamamoto in view of Akram and APA. The rejections are respectfully traversed and reconsideration is requested.

Claim 40 recites a “semiconductor device” comprising “at least one solder